

ABSTRACT OF THE DISCLOSURE

A flexible printed circuit board (FPC) comprises a base film; a base film side adhesive layer provided on the base film; a metal foil layer on which a pattern circuit is formed, provided on the base film side adhesive layer; and a cover layer side adhesive layer provided on the metal foil layer, wherein at least one of the base film side adhesive and the cover layer side adhesive layer has a higher glass transition temperature than the working environment temperature of the flexible printed circuit board, so that the FPC has a stable flexibility at high temperature.

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